

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,888,228 B1
DATED : May 3, 2005
INVENTOR(S) : Mostafazadeh et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 1,

Line 19, delete "However, as".

Lines 38-56, delete "A temporary support fixture provides support and stability to a thin lead frame panel having the fine geometries required for high-density IC chip interfaces. An embodiment of the support fixture includes an adhesive pad made of one-sided sticky tape mounted to a rigid frame made of stainless steel, the rigid frame maintaining the adhesive pad in a fixed configuration providing a stable flat surface for support of the lead frame panel. Alternatively, the rigid frame and adhesive pad can be made of any materials compatible with the IC package manufacturing process and capable of supporting the lead frame panel through the manufacturing process. The adhesive pad can also be patterned to ease the manufacturing process. The rigid frame can include positioning features to assist in the alignment of the lead frame and adhesive pad. If encapsulant material is to be dispensed over the lead frame panel, a containment dam can be formed around the lead frame after it is installed on the adhesive pad, to provide a boundary for encapsulant material flow".

Column 2,

Line 17, delete "typical".

Line 18, change "ne embodiment" to -- one embodiment --.

Column 3,

Line 49, change "panel 10" to -- panel 110 --.

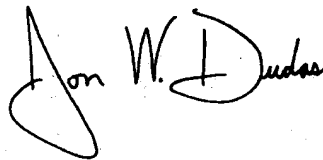
Column 6,

Line 30, change "multiplicity ay of" to -- multiplicity of --.

Line 54, change "that substantially" to -- that are substantially --.

Signed and Sealed this

Twenty-sixth Day of July, 2005



JON W. DUDAS

Director of the United States Patent and Trademark Office